

FX6KMJ-2

High-Speed Switching Use Pch Power MOS FET

REJ03G0262-0100 Rev.1.00 Aug.20.2004

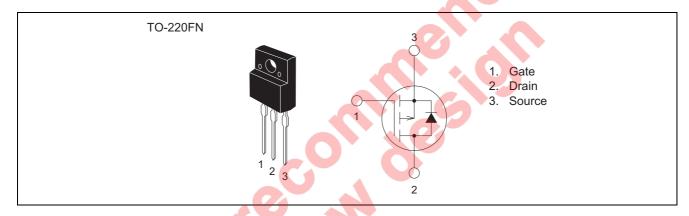
Features

 $\begin{array}{ll} \bullet & Drive\ voltage: 4\ V \\ \bullet & V_{DSS}: -100\ V \\ \bullet & r_{DS(ON)\ (max)}: 0.58\ \Omega \end{array}$

• $I_D:-6A$

• Recovery Time of the Integrated Fast Recovery Diode (TYP.): 80 ns

Outline



Applications

Motor control, lamp control, solenoid control, DC-DC converters, etc.

Maximum Ratings

 $(Tc = 25^{\circ}C)$

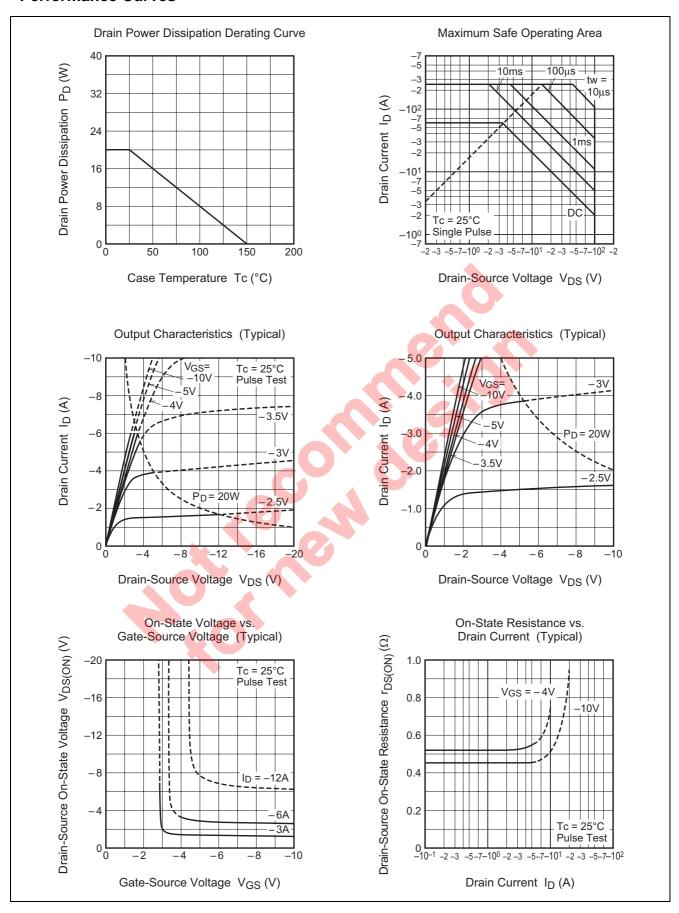
Parameter	Symbol	Ratings	Unit	Conditions
Drain-source voltage	V _{DSS}	-100	V	V _{GS} = 0 V
Gate-source voltage	V _{GSS}	±20	V	$V_{DS} = 0 V$
Drain current	I _D	-6	А	
Drain current (Pulsed)	I _{DM}	-24	Α	
Avalanche current (Pulsed)	I _{DA}	-6	Α	L = 100 μH
Source current	Is	-6	Α	
Source current (Pulsed)	I _{SM}	-24	Α	
Maximum power dissipation	P _D	20	W	
Channel temperature	Tch	- 55 to +150	°C	
Storage temperature	Tstg	- 55 to +150	°C	
Isolation voltage	Viso	2000	V	AC 1 minute,
				Terminal to case
Mass	_	2.0	g	Typical value

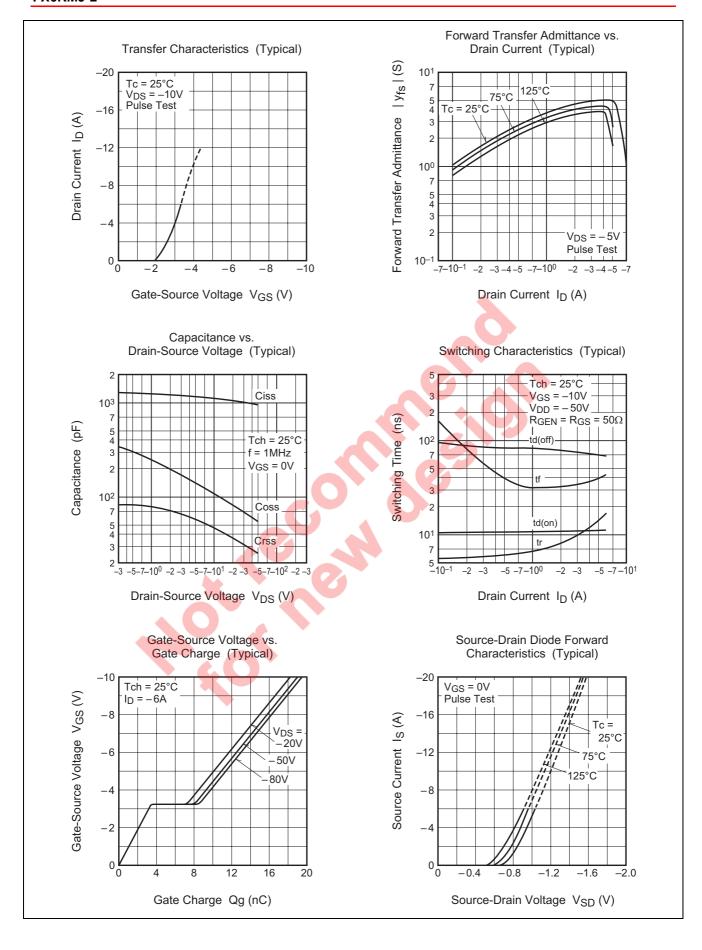
Electrical Characteristics

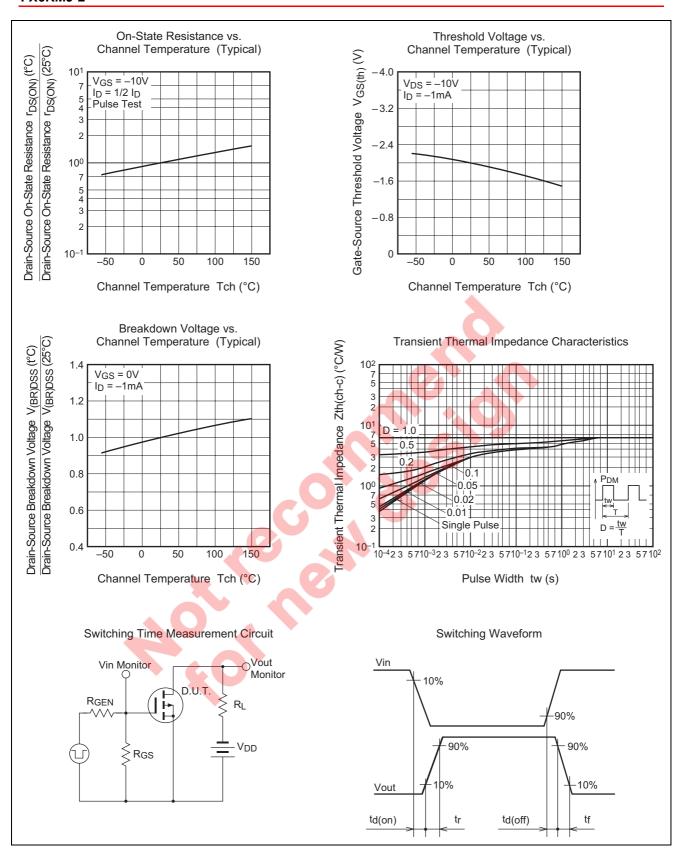
 $(Tch = 25^{\circ}C)$

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test conditions
Drain-source breakdown voltage	V _{(BR)DSS}	-100	_	_	V	$I_D = -1 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate-source leakage current	I _{GSS}	_	_	±0.1	μΑ	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$
Drain-source leakage current	I _{DSS}			-0.1	mA	$I_D = -1 \text{ mA}, V_{GS} = 0 \text{ V}$
Gate-source threshold voltage	$V_{GS(th)}$	-1.0	-1.5	-2.0	V	
Drain-source on-state resistance	r _{DS(ON)}	_	0.46	0.58	Ω	$I_D = -3 \text{ A}, V_{GS} = -10 \text{ V}$
Drain-source on-state resistance	r _{DS(ON)}	_	0.55	0.72	Ω	$I_D = -3 \text{ A}, V_{GS} = -4 \text{ V}$
Drain-source on-state voltage	V _{DS(ON)}	_	-1.38	-1.74	V	$I_D = -3 \text{ A}, V_{GS} = -10 \text{ V}$
Forward transfer admittance	y _{fs}	_	4.7	_	S	$I_D = -3 \text{ A}, V_{DS} = -5 \text{ V}$
Input capacitance	Ciss	_	1110	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V},$
Output capacitance	Coss	_	108	_	pF	f = 1MHz
Reverse transfer capacitance	Crss	_	44	_	pF	
Turn-on delay time	t _{d(on)}	_	9	_	ns	$V_{DD} = -50 \text{ V}, I_D = -3 \text{ A},$
Rise time	t _r	_	8	_	ns	
Turn-off delay time	t _{d(off)}		72	_	ns	$R_{GEN} = R_{GS} = 50 \Omega$
Fall time	t _f	_	33	_	ns	
Source-drain voltage	V_{SD}	_	-1.0	-1.5	V	$I_{S} = -3 \text{ A}, V_{GS} = 0 \text{ V}$
Thermal resistance	Rth(ch-c)			6.25	°C/W	Channel to case
Reverse recovery time	t _{rr}	_	80		ns	$I_{S} = -6 \text{ A}, \text{ dis/dt} = 100 \text{ A/}\mu\text{s}$
		0		0		
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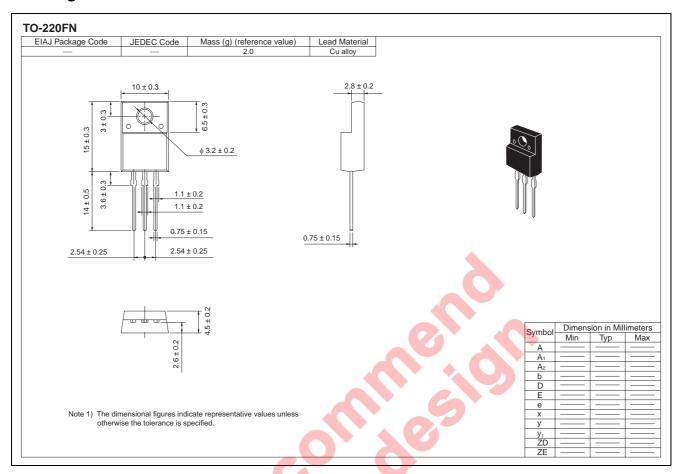
Performance Curves







Package Dimensions



Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Plastic Magazine (Tube)	50	Type name	FX6KMJ-2
Lead form	Plastic Magazine (Tube)	50	Type name – Lead forming code	FX6KMJ-2-A8

Note: Please confirm the specification about the shipping in detail.

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